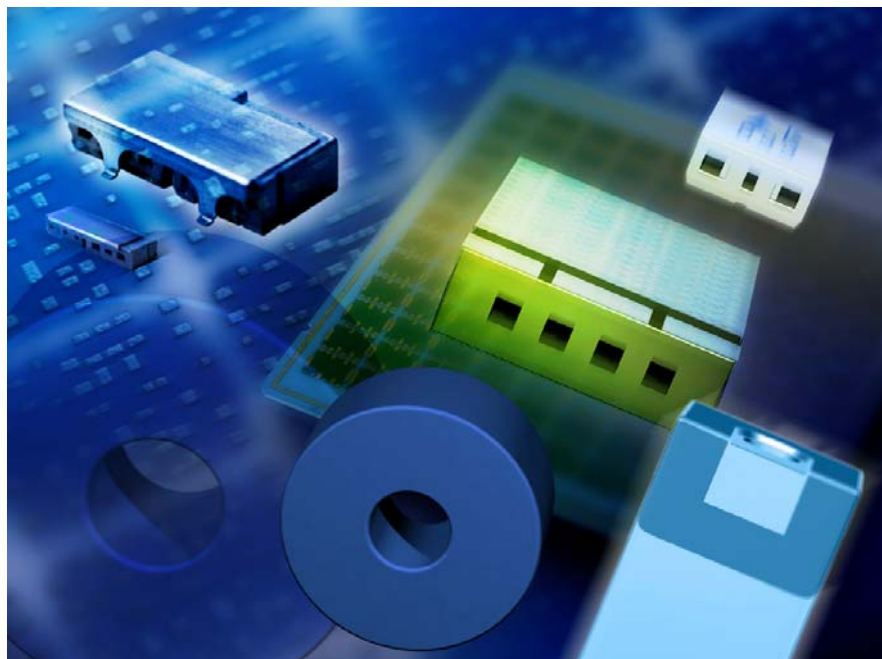


Preliminary Data Sheet



**Features**

- Low Profile (maximum height 1.2 mm)
- SMD filter consisting of coupled resonators with stepped impedances
- Low losses
- High attenuations at GSM (900, 1800, 1900) and UMTS bands
- High attenuation at 2 times center frequency
- Excellent reflow solderability, no migration effect due to copper/tin metallization

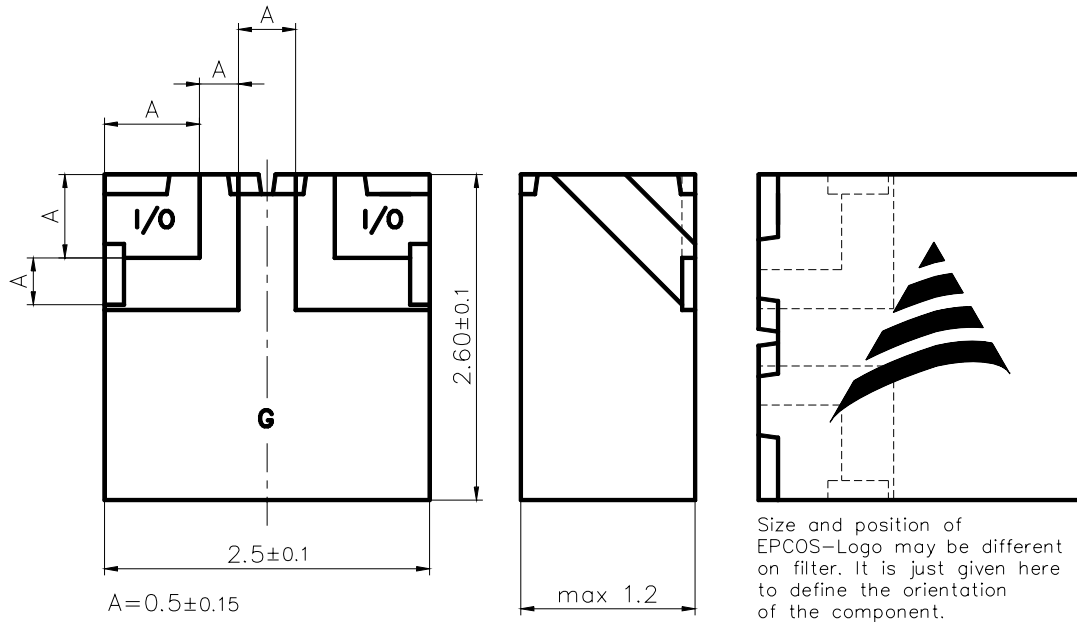
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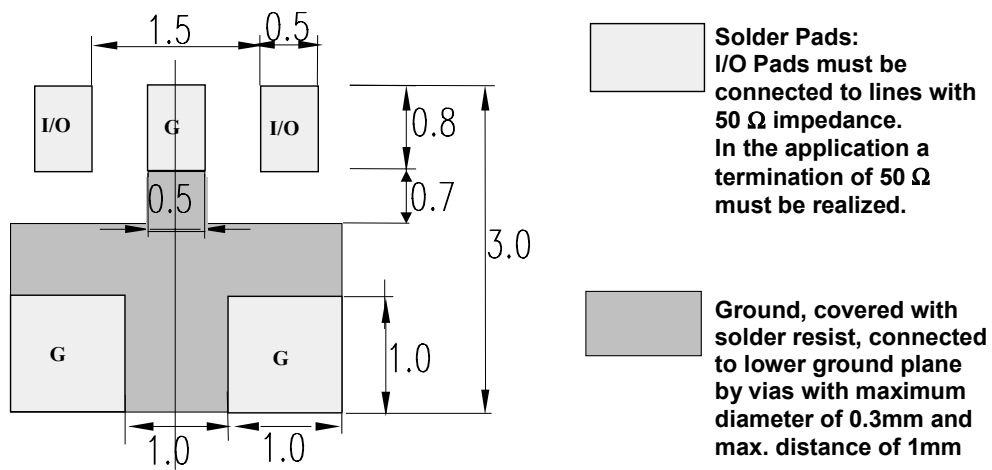
Preliminary Data Sheet

Dimension Limits , Marking



View from below onto the solder terminals and view from beside

Recommended footprint (Same Footprint as for „X“101 and „X“201 Wlan-Series )



Preliminary Data Sheet

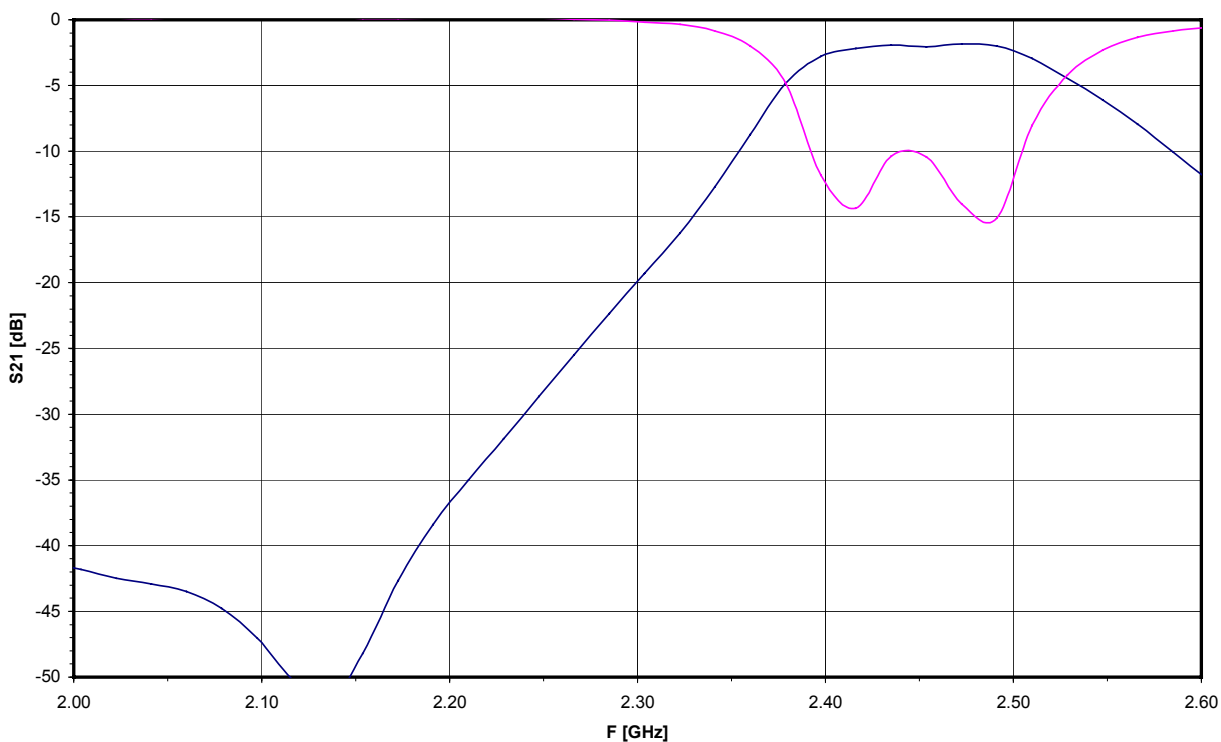
Characteristics (over whole temperature range)

		min.	typ.	max.	
Center frequency	$f_C$	-	2.450	-	GHz
Insertion loss in Passband	$\alpha_{IL}$		2.2	2.5	dB
Passband (2400- 2500)	$B$	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.5	0.8	dB
Return Loss in dB / Standing wave ratio			-11 / 1.8	-9.5 / 2.0	
Impedance	$Z$		50		$\Omega$
Attenuation	$\alpha$				
	at DC to 1580 MHz	40	43		dB
	at 1805 to 1990 MHz	38	41		dB
	at 2110 to 2170 MHz	35	37		dB
	at 3200 to 4600 MHz	20	25		dB
	at 4800 to 5000 MHz	25	30		dB
RF input power (2400 – 2500 MHz)				30	dBm

Maximum ratings

IEC climatic category (IEC 68-1)		- 40 /+ 90/56	
Operating temperature	$T_{Op}$	- 40 / + 85	°C

Typical passband characteristics



Preliminary Data Sheet

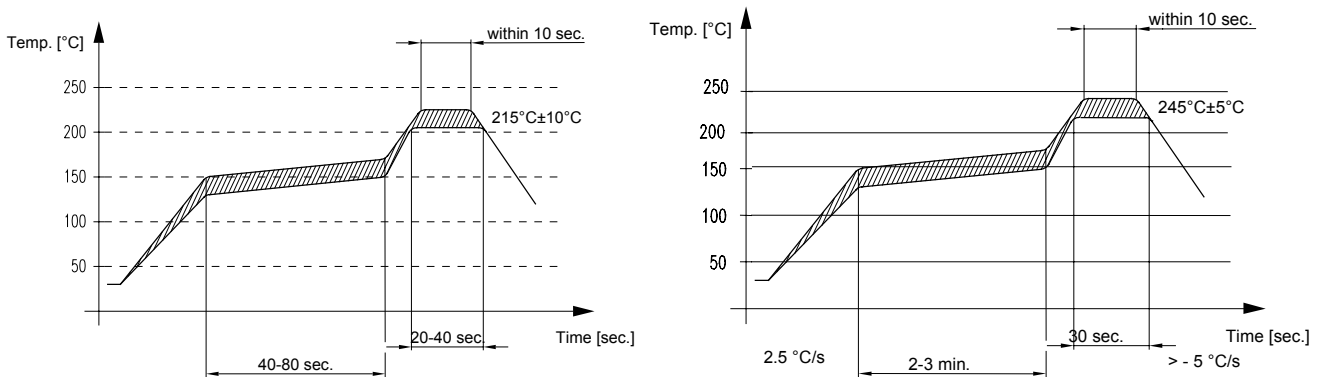
Processing information

Wettability acc. to IEC 68-2-58:  $\geq 75\%$  (after aging)

Soldering Requirements

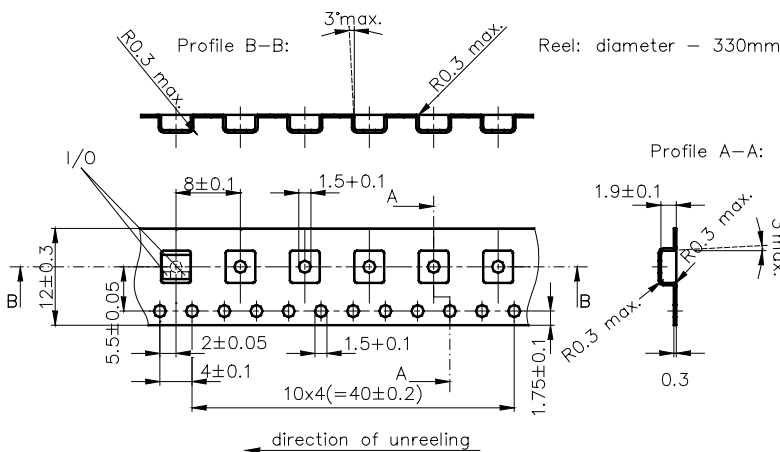
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	$^{\circ}\text{C}$ $^{\circ}\text{C}$

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: 4000



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